

**AMENDMENTS TO THE DRAWINGS**

Attached hereto are two (2) sheets of corrected formal drawings. The corrected formal drawings incorporate the following drawing changes:

**In FIG. 1, the term “MANAGE AND CONTROL UNIT” has been replaced by the term “MANAGEMENT AND CONTROL UNIT.”**

**In FIG. 2, the term “MANAGE AND CONTROL UNIT” has been replaced by the term “MANAGEMENT AND CONTROL UNIT.” The term “ANALYSIS RESULTS” has been replaced by the term “ANALYSIS RESULT” in steps 205, 206, and 207. The term “RESPONDING” has been replaced by the term “SENDING” in step 207.**

It is respectfully requested that the corrected formal drawings be approved and made a part of the record of the above-identified application.

Attachment: Replacements sheets  
Annotated sheets showing changes

### **REMARKS**

Applicants appreciate the Examiner's thorough consideration provided the present application. Claims 1, 10, 11, 12 and 20 are now present in the application. The specification, abstract, drawings and claims 1, 10, 11, 12 and 20 have been amended. Reconsideration of this application, as amended, is respectfully requested.

#### **Specification Objection**

The specification and abstract have been amended to remove the typographical errors. The specification is revised carefully in order to comply with 35 U.S.C. 112, first paragraph. Applicants respectfully submit that no new matter is entered. Entry of the above amendments to the specification is earnestly solicited.

#### **Drawings**

Applicants have submitted two (2) sheets of corrected formal drawings. Reconsideration is respectfully requested.

#### **Claim Objections**

Claims 1, 10, 11, 12 and 20 have been amended. Reconsideration and withdrawal of this objection are respectfully requested.

### **Claim Rejections Under 35 U.S.C. §102**

Claims 1, 10-12, and 20 stand rejected under 35 U.S.C. §102(b) as being anticipated by Vinciarelli (US Patent No. 6,110,213). This rejection is respectfully traversed.

Vinciarelli discloses a fabrication rules based automated design and manufacturing system and method. The automated custom power supply design and manufacturing system uses an expert system containing a set of rules, including manufacturing limitations to limit design choices and ensure feasibility and manufacturability of the design. A design interface collects specifications from a user. A complement of power components for satisfying the electrical specifications is defined and mechanical specifications for each component are provided by the system for use in creating the mechanical design. After the mechanical design is established a thermal analysis is performed and the completed design is returned to a host computer. After an order is received, a computer integrated manufacturing system generates all of the specifications required to manufacture the components for the system and the system.

Regarding claim 12, Vinciarelli fails to teach every element of claim 12 of the claimed invention. In col. 4, lines 15-21 of Vinciarelli, the custom power supply may include a user-defined package and the power supply specifications. In claim 12 of the claimed invention, the required information is selected from the group consisting of substrate information, die dimension information, thermal performance information, substrate layer information, input terminal information, output terminal information, and terminal pitch information of a semiconductor package. The required information in claim 12 is aimed at semiconductor package, but Vinciarelli is aimed at custom power supply. Therefore, it is respectfully submitted that the required information is different from that in Vinciarelli. The difference between claim

12 and Vinciarelli is so obvious that there is no reason for Examiner to reject the claim 12 under 35 U.S.C. §102(b) as being anticipated by Vinciarelli. Moreover, because the difference between claim 12 and Vinciarelli is obvious, how can one skilled in the art directly imitate Vinciarelli relating to automatically designing custom power supply to undoubtedly get the claimed invention relating to semiconductor package? Vinciarelli actually fails to render the claimed invention unpatentable.

Regarding claim 20, Vinciarelli fails to teach the analysis module, wherein the analysis module is selected from the group consisting of a thermal analysis module, a circuit analysis module, a stress analysis module, a reliability module, a material analysis module and a substrate analysis module. In col. 1, lines 30-35 of Vinciarelli, *a typical power supply may involve qualification and testing of proto-types of with respect to electrical, thermal, mechanical and EMI/RFI specifications*. The analysis module in claim 20 is different from Vinciarelli. Vinciarelli actually fails to render the claimed invention unpatentable.

Regarding claim 1, and its dependent claims 10 and 11, Examiner didn't compare the claimed invention to the citation, Vinciarelli. System claims 1 and 10-11 are traversed based on the same rationale as noted above.

Regarding claim 1, Vinciarelli fails to teach every element of claim 1 of the claimed invention. The required information in claim 1 is selected from the group consisting of substrate information, die dimension information, thermal performance information, substrate layer information, input terminal information, output terminal information, and terminal pitch information of a semiconductor package. It is respectfully submitted that the required information is aimed at semiconductor package, and therefore the required information is

different from that in Vinciarelli. Vinciarelli actually fail to render the claimed invention unpatentable.

Regarding claim 10, in claim 10 of Vinciarelli the automated power supply design system further comprises: a production scheduler connected to receive said component specifications and to allocate a time slot for production of said at least one component by said CIM facility. Vinciarelli fails to teach the feature of claim 10, wherein said schedule information includes progress information of processing said semiconductor package order and result information of processing said semiconductor package order.

Regarding claim 11, Vinciarelli fails to teach the analysis module in claim 11, wherein said analysis module is selected from the group consisting of a thermal analysis module, a circuit analysis module, a stress analysis module, a reliability module, a material analysis module, and a substrate analysis module. Vinciarelli actually fail to render the claimed invention unpatentable.

In light of the above remarks to the claims, Applicant contends that currently amended Claim 1, 10, 11, 12 and 20 are patentable thereover. The claims are in condition for favorable consideration and Applicants respectfully request that a timely Notice of Allowance be issued in this case.

### **CONCLUSION**

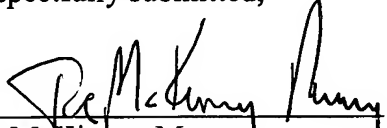
It is believed that a full and complete response has been made to the Office Action, and that as such, the Examiner is respectfully requested to send the application to Issue.

In the event there are any matters remaining in this application, the Examiner is invited to contact Joe McKinney Muncy, Registration No. 32,334 at (703) 205-8000 in the Washington, D.C. area.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional fees required under 37 C.F.R. §§1.16 or 1.17; particularly, extension of time fees.

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Respectfully submitted,

By   
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Attachments: Replacement Sheets  
Annotated Sheets Showing Changes  
Substitute Specification  
A Marked-up Copy of the Substitute Specification

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